# Product End-of-Life Disassembly Instructions

**Product Category:** Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

- HP ProDisplay P222c 21.5-inch Video Conferencing Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1. Items listed below are classified as requiring selective treatment.
2. Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm IF BD, POWER BD, F/K BD</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USB cable, VGA cable, Display cable, Power cord</td>
<td>4</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(HEX HEAD)</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Stand/Base Assy From Display Head
2. Remove Rear Cover Assy From Display Head
3. Remove Front Cover Assy and Webcam Assy From Display Head
4. Remove Key Board and Speaker from Front Cover Assy
5. Disassemble Front Cover ASSY
6. Disassemble Webcam ASSY
7. Take 4pcs Al foil Off From Chassis Cover & Remove Panel
8. Take 10pcs Screw then remove Interface BD and Power BD
9. Press release Base Button than remove Stand Assy from Base Assy
10. Disassemble Stand Assy
11. Disassemble Base Assy
12. LCD Panel explode

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP P2222c Disassembly Process

- Kite Hong
- Mechanical Engineer
- April-14-2015
External Electric Cables Dissecting Process

Remove Cable From Display Head.

Dissecting To Complete.
Remove Stand Base From Display Head

Press the release button and remove Stand Base Assy from Display Head.
Remove Rear Cover From Display Head

Remove 4pcs wall mount screws and 4pcs hinge BRKT screws from display head.

Remove Rear Cover From Display Head.
7. Remove Webcam cable, F/K cable, Speaker cable and 2pcs acetate tape from display head.

Remove Webcam Assy and Front Cover Assy.
Remove Key Board and speaker Off From Front Cover

8. Remove F/K board and Speaker from FC
Disassemble Front Cover ASSY

- Front cover
- Webcam door
- Function key
- Webcam On/Off Button
- Speaker Mesh
Disassemble Webcam ASSY
Disassembly Chassis and Panel ASSY

1. Remove Panel LED connector from panel.
2. Remove 4pcs Al foil off from Chassis cover.
3. Remove LVDS connector off from Panel.
4. Remove the panel.
**Disassembly Chassis Assy**

1. **Remove** 6pcs Screw from P.C.B

2. **Remove** 2pcs AC Screw and 2pcs VGA screw
Disassemble Stand and Base Assy

Press the release Button then remove stand from base
Disassemble Stand Assy

remove 6pcs screw from stand cover and hinge BRKT
Disassemble Base Assy

Remove 4pcs screw and 6pcs rubber from base BRKT
1. Remove the mylar shield cover

2. Dismantle C/Top

3. Separate C/Top (push the C/Top because of damages on COF)

4. Separate B/Ass’y
LCD PANEL EXPLODE

5. Loosen B/L Screw (*5)
6. Dismantle G/Panel
7. Removeal Optical sheets
8. Removeal LGP
16

9. Removal Reflector

10. Separate LED Array from C/Bottom Assy

11. LED Array

Dissecting to complete.